Power Inductor

HPC4012TF-SERIES

| | ECN HISTORY LIST | | | | | | | |
|-----|------------------|-------------|----------|---------|-------|--|--|--|
| REV | DATE | DESCRIPTION | APPROVED | CHECKED | DRAWN | | | |
| 1.0 | 17/04/12 | 新 發 行 | 羅宜春 | 梁周虎 | 張光 | | | |
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Power Inductor

HPC4012TF-SERIES

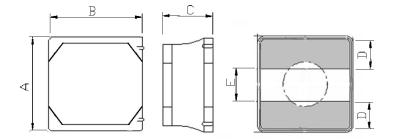
1. Features

- 1. This specification applies Low Profile Power Inductors.
- 2. 100% Lead(Pb) & Halogen-Free and RoHS compliant.

2. Dimension







| Series | A(mm) | B(mm) | C(mm) | D(mm) | E(mm) |
|-----------|---------|---------|----------|----------|----------|
| HPC4012TF | 4.0±0.2 | 4.0±0.2 | 1.2 max. | 1.2 ref. | 1.6 ref. |

Units: mm

3. Part Numbering

| HPC | 4012 | TF | - | 100 | M |
|------------|-------------|----|---|-----|---|
| Α | В | С | | D | Е |

A: Series

B: Dimension

C: Lead Free

D: Inductance 100=10uH

E: Inductance Tolerance M=±20%; Y=±30%

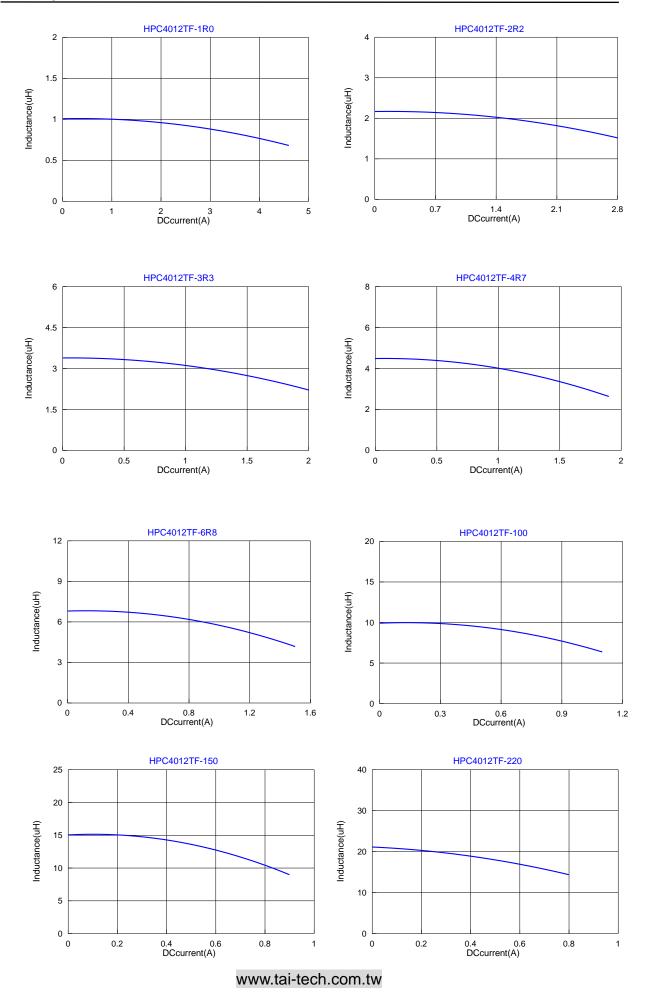
4. Specification

| TAI-TECH Part Number | Inductance (uH) | Tolerance (%) | Test Frequency (Hz) | SRF (MHz) typ. | DCR (Ω) ±20% | I sat (A)typ. | I sat (A)Max. | I rms (A)typ. | I rms (A)Max. |
|-------------------------|--------------------|------------------|------------------------|-------------------|-----------------|------------------|------------------|------------------|------------------|
| HPC4012TF -1R0Y | 1.0 | ±30% | 1V100K | 100 | 0.042 | 3.30 | 2.80 | 2.50 | 2.20 |
| HPC4012TF -2R2M | 2.2 | ±20% | 1V100K | 70 | 0.060 | 1.95 | 1.65 | 2.20 | 1.90 |
| HPC4012TF -3R3M | 3.3 | ±20% | 1V100K | 60 | 0.070 | 1.60 | 1.40 | 1.90 | 1.70 |
| HPC4012TF -4R7M | 4.7 | ±20% | 1V100K | 45 | 0.095 | 1.40 | 1.20 | 1.70 | 1.50 |
| HPC4012TF -6R8M | 6.8 | ±20% | 1V100K | 35 | 0.125 | 1.10 | 0.90 | 1.50 | 1.30 |
| HPC4012TF -100M | 10 | ±20% | 1V100K | 30 | 0.180 | 1.00 | 0.80 | 1.30 | 1.10 |
| HPC4012TF -150M | 15 | ±20% | 1V100K | 24 | 0.260 | 0.80 | 0.65 | 0.95 | 0.75 |
| HPC4012TF -220M | 22 | ±20% | 1V100K | 18 | 0.400 | 0.60 | 0.50 | 0.72 | 0.62 |

Note:

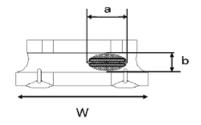
 $\mbox{lsat}: \mbox{Based on inductance change} \quad (\, \triangle \mbox{L/L0}: \leq 30\% \,) \ @ \mbox{ ambient temp. } 25\%$

Irms: Based on temperature rise $(\triangle T : 40^{\circ}C \text{ typ.})$ max



Void appearance tolerance Limit

Size of voids occurring to coating resin is specified below.

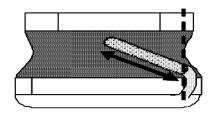


Appearance of exposed wire tolerance limit :

- 1. Width direction (dimension a): Acceptable when a \leq w/2 Nonconforming when a > w/2
- 2. Length direction (dimension b): Dimension b is not specified.
- 3. The total area of exposed wire occurring to each sides is not greater than 50% of coating resin area, and is acceptable.

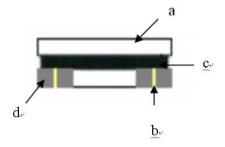
External appearance criterion for exposed wire

Exposed end of the winding wire at the secondary side should be 2mm and below.



5. Material

| No. | Description | Specification |
|-----|-------------|------------------------------------|
| a. | Core | Ferrite Core |
| b. | Wire | Enameled Copper Wire |
| С | Glue | Epoxy / Epoxy with magnetic powder |
| d | Terminal | Ag/Ni/Sn |



6. Reliability and Test Condition

| Item | Performance | Test Condition |
|-------------------------------|--|---|
| Operating temperature | -40~+125℃ (Including self - temperature rise) | |
| Storage temperature | -40~+125℃ (on board) | |
| Electrical Performance Tes | st | |
| la destar a c | | HP4284A,CH11025,CH3302,CH1320,CH1320S |
| Inductance | Refer to standard electrical characteristics list. | LCR Meter. |
| DCR | | CH16502,Agilent33420A Micro-Ohm Meter. |
| Saturation Current (Isat) | △L≦30% typical. | Saturation DC Current (Isat) will cause L0 |
| Saturation Current (Isat) | AL = 50% typical. | to drop △L(%)(keep quickly). |
| | | Heat Rated Current (Irms) will cause the coil temperature rise |
| Heat Rated Current (Irms) | Approximately △T≦40°C | △T(°C) without core loss. |
| Trout realisa Surrent (IIIIs) | | 1.Applied the allowed DC current(keep 1 min.). |
| | | 2.Temperature measured by digital surface thermometer |
| Reliability Test | | |
| Life Test | | Preconditioning: Run through IR reflow for 2 times.(IPC/JEDEC J-STD-020DClassification Reflow Profiles) Temperature: 125±2°C (Inductor) Applied current: rated current Duration: 1000±12hrs Measured at room temperature after placing for 24±2 hrs |
| Load Humidity | | Preconditioning: Run through IR reflow for 2 times.(IPC/JEDEC J-STD-020DClassification Reflow Profiles Humidity: 85±2% R.H, Temperature: 85°C±2°C Duration: 1000hrs Min. with 100% rated current Measured at room temperature after placing for 24±2 hrs |
| Moisture Resistance | Appearance: No damage. Inductance: within±10% of initial value Q: Shall not exceed the specification value. RDC: within ±15% of initial value and shall not exceed the specification value | Preconditioning: Run through IR reflow for 2 times.(IPC/JEDEC J-STD-020DClassification Reflow Profiles 1. Baked at50°C for 25hrs, measured at room temperature after placing for 4 hrs. 2. Raise temperature to 65±2°C 90-100%RH in 2.5hrs, and keep 3 hours, cool down to 25°C in 2.5hrs. 3. Raise temperature to 65±2°C 90-100%RH in 2.5hrs, and keep 3 hours, cool down to 25°C in 2.5hrs. 4. Keep at 25°C for 2 hrs then keep at -10°C for 3 hrs 4. Keep at 25°C 80-100%RH for 15min and vibrate at the frequency of 10 to 55 Hz to 10 Hz, measure at room temperature after placing for 1–2 hrs. |
| Thermal shock | | Preconditioning: Run through IR reflow for 2 times.(IPC/JEDEC J-STD-020DClassification Reflow Profiles Condition for 1 cycle Step1: -40±2°C 30±5min Step2: 25±2°C ≤0.5min Step3: 125±2°C 30±5min Number of cycles: 500 Measured at room temperature after placing for 24±2 hrs |
| Vibration | | Oscillation Frequency: 10~2K~10Hz for 20 minutes Equipment: Vibration checker Total Amplitude:1.52mm±10% Testing Time: 12 hours(20 minutes, 12 cycles each of 3 orientations) • |

| Item | Performance | Test Condition | | | | | |
|------------------------------------|--|--|--|---|--|------------------------------------|--|
| | | Туре | Peak value (g's) | Norma duration (D) (ms | Wave form | Velocity change (Vi)ft/sec | |
| Shock | | SMD | 50 | 11 | Half-sine | 11.3 | |
| | | Lead | 50 | 11 | Half-sine | 11.3 | |
| | Appearance: No damage. Inductance: within±10% of initial value Q: Shall not exceed the specification value. | | | | along 3 perper | ndicular axes. | |
| Bending | RDC: within ±15% of initial value and shall not exceed the specification value | Shall be mounted on a FR4 substrate of the following dimensions: >=0805:40x100x1.2mm <0805:40x100x0.8mm Bending depth: >=0805inch(2012mm):1.2mm <0805 inch(2012mm):0.8mm duration of 10 sec. | | | | | |
| Soderability | More than 95% of the terminal electrode should be covered with solder • | Preheat: 150°C,60sec. Solder: Sn96.5% Ag3% Cu0.5% Temperature: 245±5°C Flux for lead free: Rosin. 9.5% Dip time: 4±1sec Depth: completely cover the termination | | | | | |
| Resistance to Soldering Heat | Appearance: No damage. Inductance: within±10% of initial value Q: Shall not exceed the specification value. RDC: within ±15% of initial value and shall not exceed the specification value | Temper (°C) 260 ±5(temp) | aaldar | ime(s) | Temperature ramp/immersion and emersion ra | ite | |
| Terminal Strength | | times.(II Reflow F With the tested, a inch(201 of a devi This forc shall be not to ap tested. | PC/JEDEC Profiles componen apply a force 2mm):1kg ce being te se shall be a applied gra | J-STD-02 t mounted e (>0805 , <=0805 i, sted. applied for dually as t to the co | ess tool | he device to be 5kg)to the side | |

7. Soldering and Mounting

7-1. Soldering

Mildly activated rosin fluxes are preferred. TAI-TECH terminations are suitable for all wave and re-flow soldering systems. If hand soldering cannot be avoided, the preferred technique is the utilization of hot air soldering tools.

7-1.1 Solder re-flow:

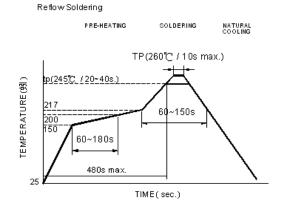
Recommended temperature profiles for re-flow soldering in Figure 1.

7-1.2 Soldering Iron(Figure 2):

Products attachment with a soldering iron is discouraged due to the inherent process control limitations. In the event that a soldering iron must be employed the following precautions are recommended.

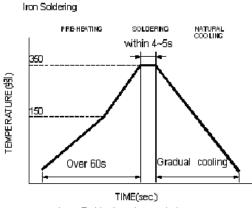
- Preheat circuit and products to 150°C
- Never contact the ceramic with the iron tip
- · Use a 20 watt soldering iron with tip diameter of 1.0mm

- 355°C tip temperature (max)
- 1.0mm tip diameter (max)
- Limit soldering time to 4~5 sec.



Reflow times: 3 times max.

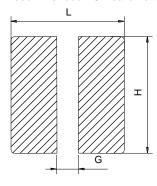
Fig.1



Iron Soldering times: 1 times max.

Fig.2

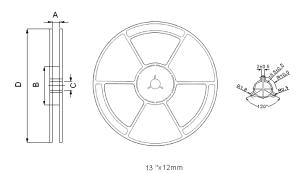
7-2. Recommended PC Board Pattern



| L(mm) | G(mm) | H(mm) |
|-------|-------|-------|
| 4.2 | 1.2 | 4.2 |

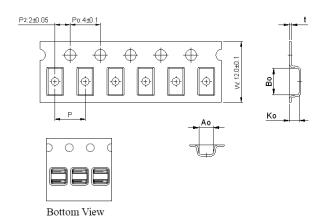
8. Packaging Information

8-1. Reel Dimension



| Туре | A(mm) | B(mm) | C(mm) | D(mm) |
|----------|--------|---------|----------|---------|
| 13"x12mm | 12±1.5 | 100±0.5 | 13.2±0.5 | 330±0.5 |

8-2. Tape Dimension / 12mm

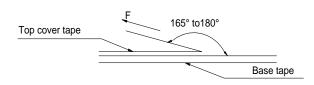


| Series | Size | Bo(mm) | Ao(mm) | Ko(mm) | P(mm) | t(mm) |
|--------|------|----------|----------|----------|----------|-----------|
| HPC | 4012 | 4.35±0.1 | 4.50±0.1 | 1.55±0.1 | 8.0±0.10 | 0.25±0.05 |

8-3. Packaging Quantity

| Chip size | 4012 |
|-------------|------|
| Chip / Reel | 4500 |

8-4. Tearing Off Force



The force for tearing off cover tape is 15 to 80 grams in the arrow direction under the following conditions.

| Room Temp. | Room Humidity | Room atm | Tearing Speed |
|------------|---------------|----------|---------------|
| (℃) | (%) | (hPa) | mm/min |
| 5~35 | 45~85 | 860~1060 | 300 |

Application Notice

- Storage Conditions(component level)
- To maintain the solderability of terminal electrodes:
- 1. TAI-TECH products meet IPC/JEDEC J-STD-020D standard-MSL, level 1.
- 3. Recommended products should be used within 12 months form the time of delivery.
- 4. The packaging material should be kept where no chlorine or sulfur exists in the air.
- Transportation
 - 1. Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
 - 2. The use of tweezers or vacuum pick up is strongly recommended for individual components.
 - 3. Bulk handling should ensure that abrasion and mechanical shock are minimized.

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